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(54) **THERMOELECTRIC MODULE**

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(71) Applicant: **LG INNOTEK CO., LTD.**, Seoul (KR)

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(57) **ABSTRACT**

Related U.S. Application Data

(63) Continuation of application No. 17/881,179, filed on Aug. 4, 2022, now Pat. No. 11,980,098, which is a continuation-in-part of application No. 16/782,295, filed on Feb. 5, 2020, now Pat. No. 11,723,275.

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A thermoelectric module may comprise a first metal substrate including a first through-hole; a first insulating layer disposed on the first metal substrate; a first electrode part disposed on the first insulating layer and including a plurality of first electrodes; a plurality of thermoelectric legs disposed on the first electrode part; a second electrode part disposed on the plurality thermoelectric legs and including a plurality of second electrodes; a second insulating layer disposed on the second electrode part; and a second metal substrate disposed on the second insulating layer and including a second through-hole.

